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PCN Date: 07June2011			Effective Date: 07June2011	
Title: Si53x Datasheet Revision from 1.1 to 1.2				
Originator: Jason Rock		Phone: 512-532-5997		Dept: WL Timing Marketing
Customer Contact: Kathy Haggar		Phone: 512-532-5261		Dept: Sales
PCN Type:				
Assembly	Discont	Discontinuance Package Test		
☐ Datasheet ☐ Fabrication ☐ Product Revision				
Packing	Labeling L		ocatior	n 🗌 Other
Last Order Date: N/A				
PCN Details				
Description of Change:				
Silicon Labs is pleased to announce rev 1.2 for the Si530, Si531, Si532, Si533, Si534 devices. Please refer to Appendix A for a list of document changes and access to these datasheets online.				
Reason for Change: To ensure datasheets are consistent with the functionality of the Si53x devices				
Impact on Form, Fit, Function, Quality, Reliability: There is no impact on form, fit, function, quality or reliability				
Product Identification: Si530, Si531, Si532, Si533, Si534				
Last Date of Unchanged Product: N/A				
Qualification Samples: N/A				
Customer Early Acceptance Sign Off:				
Customers may approve early PCN acceptance by completing the information below:				
Early Acceptance Date:				
Name:				
Company:				
Email your early Acceptance approval to: <u>katherine.haggar@silabs.com</u>				
Qualification Data: N/A				

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# **Appendix A:**

### Si530/31 datasheet revision 1.1 to v1.2 changes:

- □ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.
- □ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.
- □ Added CMOS phase jitter specs to Table 4 on page 4.
- □ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4.
- $\square$  Separated 1.8 V, 2.5 V/3.3 V supply voltage specifications in Table 8 on page 5.
- □ Updated and clarified Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.
- □ Updated Figure 3 on page 9 and Table 12 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.

## Si532 datasheet revision 1.1 to v1.2 changes:

□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.

□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.

□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4. □ Added CMOS phase jitter specs to Table 4 on page 4.

□ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.

□ Updated Figure 3 and Table 11 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.

#### Si533 datasheet revision 1.1 to v1.2 changes:

□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.

□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.

□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4.

□ Added CMOS phase jitter specs to Table 4 on page 4.

□ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.

□ Updated Figure 3 and Table 10 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.

□ Updated contact information on page 12.

## Si533 datasheet revision 1.1 to v1.2 changes:

□ Updated 2.5 V/3.3 V and 1.8 V CML output level specifications for Table 3 on page 3.

□ Added footnotes clarifying max offset frequency test conditions for Table 4 on page 4.

□ Removed the words "Differential Modes: LVPECL/LVDS/CML" in footnote referring to AN256 in Table 4 on page 4.

□ Added CMOS phase jitter specs to Table 4 on page 4.

□ Updated ESD HBM sensitivity rating in Table 7 on page 5.

□ Updated Table 8 on page 5 to include the "Moisture Sensitivity Level" and "Contact Pads" rows.

□ Updated package diagram to include crystal impedance pin in Figure 2 on page 8.

Updated Figure 3 and Table 11 on page 9 to reflect specific marking information. Previously, Figure 3 was generic.

## Access to online datasheets:

Si530/31 Datasheet v1.2 can be found here: http://www.silabs.com/Support%20Documents/TechnicalDocs/si530.pdf

Si532 Datasheet v1.2 can be found here: http://www.silabs.com/Support%20Documents/TechnicalDocs/si532.pdf

Si533 Datasheet v1.2 can be found here: http://www.silabs.com/Support%20Documents/TechnicalDocs/si533.pdf

Si534 Datasheet v1.2 can be found here: http://www.silabs.com/Support%20Documents/TechnicalDocs/si534.pdf

W7206F1 Process Change Notice Form rev AA

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